MA2YD23

Silicon epitaxial planar type

For high frequency rectification

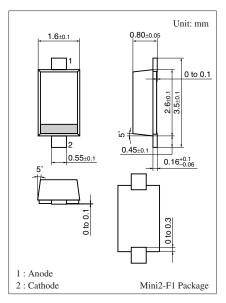
■ Features

- Forward current (Average) $I_{F(AV)} = 1$ A rectification is possible
- Low forward voltage V_F
- ullet Small reverse current I_R

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	25	V
Repetitive peak reverse voltage	V _{RRM}	25	V
Forward current (Average) *1	I _{F(AV)}	1.0	A
Non-repetitive peak forward surge current *2	I _{FSM}	3	A
Junction temperature	T _j	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note) *1: Mounted on an alumina PC board



Marking Symbol: 2W

■ Electrical Characteristics $T_a = 25$ °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 0.5 \text{ A}$		0.42	0.47	V
	V_{F2}	$I_F = 1.0 \text{ A}$		0.46	0.55	
Reverse current	I_{R1}	$V_R = 15 \text{ V}$		1.5	20.0	μΑ
	I _{R2}	$V_R = 20 \text{ V}$		2.5	40.0	

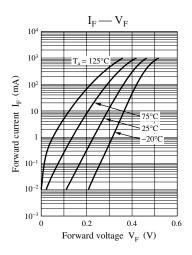
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

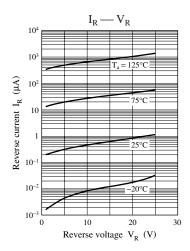
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

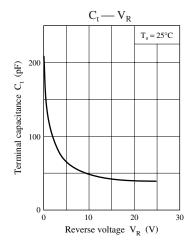
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^{*2:} The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

Panasonic







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